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Structural modulation and enhanced thermoelectric properties of thermoelectric thin films

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Solution of the main size of the thin film and enhanced thermoelectric properties with increased see beck coefficient. The enhancement of thermal power can be attributed to the increased potential barriers owing to the reduced grain size of the film. We also demonstrated this approach in other thermoelectric thin films such as SnTe. This finding provides an alternative strategy to enhance thermoelectric performance of thin films.

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